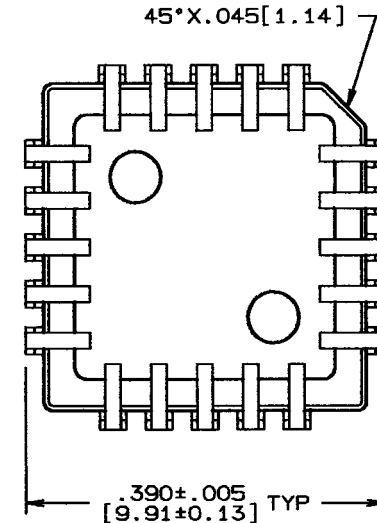
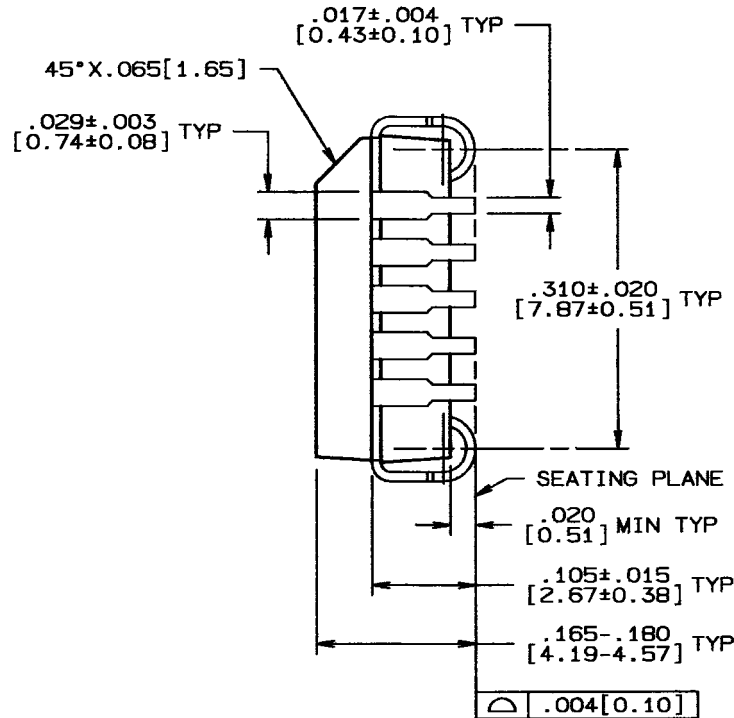
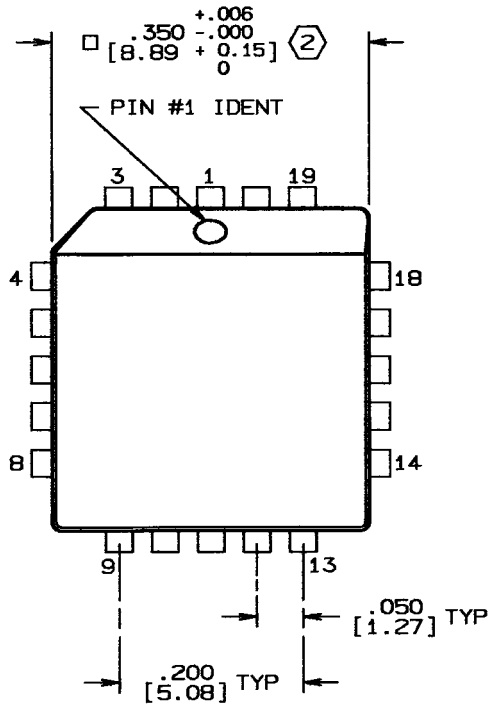


REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE & REDRAW TO STD FORMAT	09318	09/17/92	DEG/SL
L	ADD COPLANARITY & SEATING PLANE, CONVERT LIMIT DIM'S TO NOM±TOL. DIM 45°X.065[1.65] WAS 45°X.065[1.14]; DIM .390±.005 WAS .385-3.95	10036	12/01/93	MS/SL



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER THICKNESS PER SIDE ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-047, VARIATION AA, DATED 5/90.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN D. E. GRADY	09/17/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DESG. CHK. <i>Mark Squay</i>	12/03/93	PLASTIC CHIP CARRIER, SQ., .050 LD PITCH, 20 LEAD			
ENGR. CHK. <i>Sam Lion</i>	12/01/93				
APPROVAL		SCALE N/A	SIZE B	DRAWING NUMBER MKT-V20A	REV L
PROJECTION INCH [MM]		DO NOT SCALE DRAWING		SHEET 1 OF 1	